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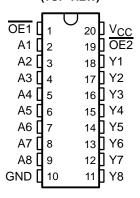
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package

description

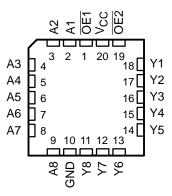
The 'ABT540 octal buffers and line drivers are ideal for driving bus lines or buffer memory address registers. The devices feature inputs and outputs on opposite sides of the package that facilitate printed circuit board layout.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable (OE1 or OE2) input is high, all corresponding outputs are in the high-impedance state.

SN54ABT540 . . . J OR W PACKAGE SN74ABT540 . . . DB, DW, N, OR PW PACKAGE (TOP VIEW)



SN54ABT540 . . . FK PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down, OE should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT540 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT540 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

	INPUTS	OUTPUT			
OE1	OE2	Α	Y		
L	L	L	Н		
L	L	Н	L		
Н	X	Χ	Z		
X	Н	Χ	Z		



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

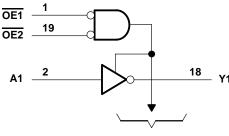
EPIC-IIB is a trademark of Texas Instruments Incorporated.



logic symbol†

1 OE1 19 ΕN OE2 2 18 Α1 ∇ **Y1** 17 3 **Y2** A2 4 16 А3 **Y3** 5 15 Α4 **Y4** 6 14 **Y5** Α5 7 13 A6 **Y6** 8 12 **Y7 A7** 9 11 **A8 Y8**

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		–0.5 V to 7 V
Voltage range applied to any output in the high	or power-off state, V _O	. −0.5 V to 5.5 V
Current into any output in the low state, IO: SNS	54ABT540	96 mA
SN	74ABT540	128 mA
Input clamp current, I _{IK} (V _I < 0)		–18 mA
Output clamp current, I _{OK} (V _O < 0)		–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	DB package	115°C/W
•	DW package	97°C/W
	N package	67°C/W
	PW package	128°C/W
Storage temperature range, T _{stg}		-65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

					SN74ABT540		UNIT
			MIN	MAX	MIN	MAX	UNIT
V _{CC} Supply voltage				5.5	4.5	5.5	V
VIH	V _{IH} High-level input voltage				2		V
VIL	V _{IL} Low-level input voltage			0.8		0.8	V
٧ _I	V _I Input voltage			Vcc	0	VCC	V
Іон	IOH High-level output current			-24		-32	mA
loL	Low-level output current		Q _C	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Q'	5		5	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A = 25°C			SN54ABT540		SN74ABT540		UNIT	
PARAI	WEIER	TEST CONDITIONS		MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNII	
۷ıK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
\/ -		$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
VOH		VCC = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2					
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2			
Vai		VCC = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V	
V _{hys}					100			2			mV	
lį		V _{CC} = 5.5 V,	$V_I = V_{CC}$ or GND			±1		± 1		±1	μΑ	
lozh		V _{CC} = 5.5 V,	$V_0 = 2.7 \text{ V}$			50		5 0		50	μΑ	
lozL		$V_{CC} = 5.5 V,$	$V_0 = 0.5 \text{ V}$			-50	~	– 50		-50	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100	3			±100	μΑ	
ICEX		$V_{CC} = 5.5 \text{ V}, V_{O} = 5.5 \text{ V}$	Outputs high			50	90	50		50	μΑ	
10 [‡]		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	– 50	-180	-50	-180	mA	
		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND	Outputs high		1	250		250		250	μΑ	
ICC			Outputs low		24	30		30		30	mA	
	_		Outputs disabled		0.5	250		250		250	μΑ	
	Data inputs		Outputs enabled			1.5		1.5		1.5		
ΔICC§			Outputs disabled			0.05		0.05		0.05	mA	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5		
Ci	V _I = 2.5 V or 0.5 V			3						pF		
Co		V _O = 2.5 V or 0.5 V			8						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT54	0 SN74	SN74ABT540	
			MIN	TYP	MAX	MIN MA	X MIN	MAX	
t _{PLH}	А	Y	1	2.9	4.1	1 8	1	4.8	ns
tPHL			1	3.1	4.3	1 0	1	4.8	
^t PZH	ŌĒ	Y	1.1	3.4	4.9	1.1	1.1	5.9	ns
t _{PZL}			1.1	3	5.8	12)	1.1	6.4	
t _{PHZ}	ŌĒ	V	1.5	5.3	6.8	01.5	1.5	7.3	ns
tPLZ		OE 1	1.2	4.4	5.7	1.2	1.2	6.2	115

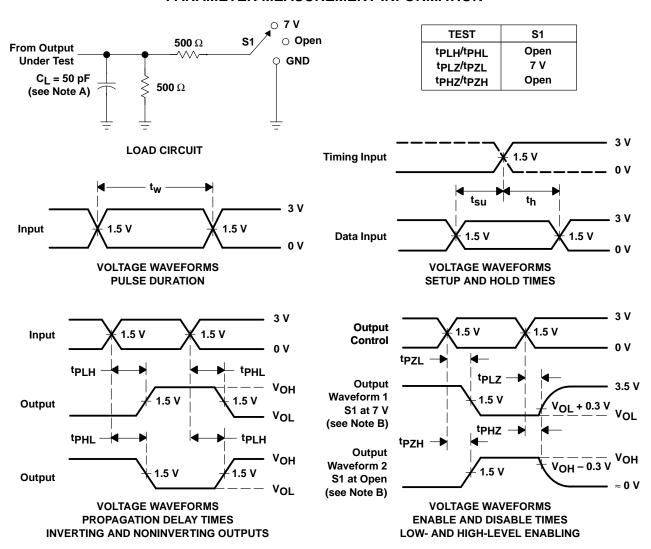


[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$, $t_{f} \leq 2.5 \text{ ns}$, $t_{f} \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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